

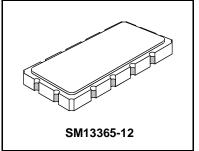
- Designed for GSM BTS Transmitter Applications
- Low Insertion Loss
- Excellent Size-to-Performance Ratio
- Hermetic 13.3 X 6.5 mm Surface-Mount Case
- Unbalanced Input and Output
 Complies with Directive 2002/95/EC (RoHS)
- Pb

Absolute Maximum Ratings

Rating	Value	Units
Maximum Incident Power in Passband	+10	dBm
Max. DC voltage between any 2 terminals	30	VDC
Storage Temperature Range	-40 to +85	°C
Suitable for lead-free soldering - Max Soldering Profile	260°C	for 30 s

211 MHz SAW Filter

SF1091A



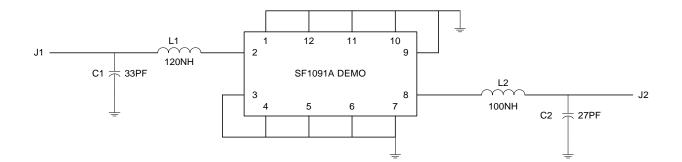
Electrical Specification

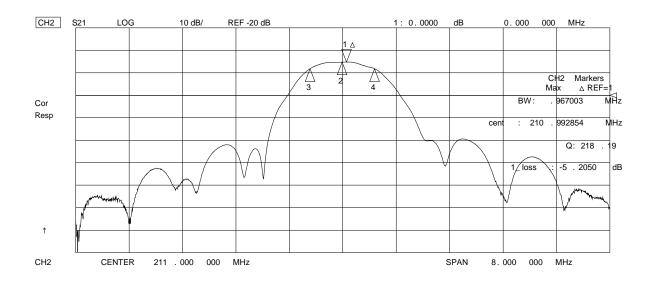
Characteristic		Sym	Notes	Min	Тур	Max	Units
Nominal Center Frequency		f _C	1		211.000	•	MHz
Passband	Insertion Loss at fc	IL	1		7	8.0	dB
	3 dB Passband	BW3	1, 2	±450	±500		kHz
	Group Delay Variation over fc ±150 kHz	GDV			200	250	ns _{P-P}
Rejection	fc-2.0 to fc-1.05 and fc+1.05 to fc+2.0 MHz		1, 2, 3	10	21		dB
	fc-80 to fc-2.0 and fc+2.0 to fc+80 MHz			30	33		
	n x fc over 291 to 2000 MHz			40	60		
Operating Temperature Range		T _A	1	-10		+85	°C
Frequency Temperature Coefficient		FTC	1		0.32		ppm/°C ²
Impedance Matching to 50 Ω unbalanced				Ext	ernal L-C		
Case Style		SM13365-12 13.3 x 6.5 mm Nominal Footprint					
Lid Symbolization (XX = 2 character date code)		RFM SF1091A XX					

CAUTION: Electrostatic Sensitive Device. Observe precautions for handling. Notes:

- 1. Unless noted otherwise, all specification apply over the operating temperature range with filter soldered to the specified demonstration board with impedanced matching to 50 Ω network analyzer.
- 2. Unless noted otherwise, all frequency specifications are referenced to the nominal center frequency, fc.
- 3. Rejection is measured as attenuation below the minimum IL point in the passband. Rejection in final user application is dependent oon PCB layout and external impedance matching design. See Application Note No. 42 for details.
- The turnover temperature, T_O, is the temperature of maximum (or turnover) frequency, f_o. The nominal frequency at any case temperature, T_c, may be calculated from: f=f_o[1-FTC(T_o-T_c)²].
- 5. The design, manufacturing process, and specifications of this filter are subject to change.
- 6. Either Port 1 or Port 2 may be used for either input or output in the design. However, impedances and impedance matching may vary between Port 1 and Port 2, so that the filter must always be installed in one direction per the circuit design.
- 7. US and international patents may apply.

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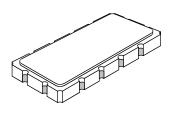




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SM13365-12 Case

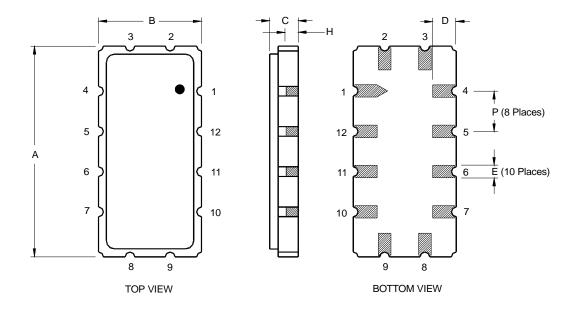
12-Terminal Ceramic Surface-Mount Case 13.3 x 6.5 mm Nominal Footprint

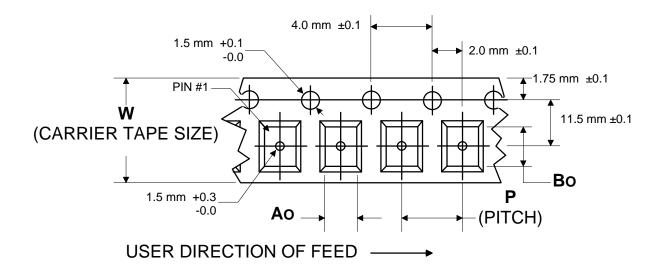


Case Dimensions						
Dimension	mm			Inches		
	Min	Nom	Max	Min	Nom	Max
Α	13.08	13.31	13.60	0.515	0.524	0.535
В	6.27	6.50	6.80	0.247	0.256	0.268
С		1.91	2.00		0.075	0.079
D		1.50			0.059	
E		0.79			0.031	
н		1.0			0.039	
Р		2.54			0.100	

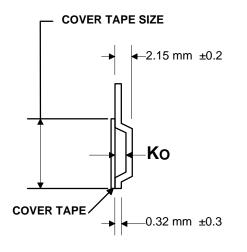
Materials				
Solder Pad	Au plating 30 - 60 ulnches (76.2-152 uM) over 80-200			
Termination	ulnches (203-508 uM) Ni.			
Lid	Fe-Ni-Co Alloy Electroless Nickel Plate (8-11% Phos-			
	phorus) 100-200 ulnches Thick			
Body	Al ₂ O ₃ Ceramic			
Pb Free	·			

Electrical Connections				
Connection		Terminals		
Port 1	Input or Return	2		
	Return or Input	3		
Port 2	Output or Return	8		
	Return or Output	9		
	Ground	All others		
Single I	Ended Operation	Return is ground		
Differer	ntial Operation	Return is hot		





COMPONENT ORIENTATION and DIMENSIONS



Carrier Tape Dimensions				
Ao	7.0 mm	±0.1		
Во	13.8 mm	±0.1		
Ко	2.2 mm	±0.1		
Pitch	12.0 mm	±0.1		
W	24.0 mm	±0.3		

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